

Simulation of Timing Determinants: Predictions and Results

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Presented to: The Factors that Limit Time Resolution in Photodetectors, Workshop 28-29 April 2011

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Remember that all models are wrong; the practical question is how wrong do they have to be to not be useful.

♦ Box & Draper, *Empirical Model-Building*, p. 74

MCP-PMT timing (rise time) breakdown

J. Milnes and J. Howorth, "Picosecond time response characteristics of microchannel plate PMT detectors," Proc. SPIE 5580, 730 (2005); doi:10.1117/12.568180

1. Cathode Gap – Small effect

 electrons emitted from cathode have a small energy (< 2eV) vs. the gap field (> 200eV).

2. MCP Stack

€

- 3. Anode Gap Similar to cathode
 - except electrons leaving MCP have significant variation in lateral velocity

"We have found that the rise time of MCP-based PMT detectors is principally governed by the variation in transit time through the MCP pores and the variation in exit velocity from the MCP stack."



MCP- Main source of rise time spread

J. Milnes & J. Howorth, "Picosecond time response characteristics of microchannel plate PMT detectors," Proc. SPIE 5580, 730 (2005); doi:10.1117/12.568180

S. Matsuura, S. Umebayashi, C. Okuyama, K. Oba, "CHARACTERISTICS OF THE NEWLY DEVELOPEDMCP AND ITS ASSEMBLY," IEEE Trans. Nuc. Sci. Vol. NS-32, 1, February 1985

- Primarily due to the many different possible path lengths (and hence transit times) of the electron avalanche through the MCP pores. Main factors:
 - Pore size: Using narrow pore MCPs would be expected to reduce the path length variation.
 - Bias angle: Uniformity of cascade initiation
 - Number of MCPs in the stack produce wider variation of path length and is therefore expected to increase rise time.
- The variation in transit time through the MCP pores is affected more by size and bias angle of the MCP pores rather than the number of MCPs.
- The spread of the rise time caused by variations in the exit velocity from the MCP stack can be severely reduced by increasing the electric field from the MCP to the anode.



- .5 [nSec/DIV]
- Fig. 13. Impulse responses of 2-stage 6µm MCP-PMT and 2-stage 12µm MCP-PMT
- Table 1 Comparison of timing characteristics of 2-stage 6µm MCP-PMT and 2-stage 12µm MCP-PMT

		6 µm Channel	12 µm Channel	
RISE TIME	(nSec)	.167	.245	
FALLTIME	(nSec)	.721	.716	
TRANSIT TIME	(nSec)	.406	.650	
TRANSIT TIME SPREAD	(nSec)	.067	.081	



Experimental results: MCP-PMT

MCP-PMT: transit time & gain



Burle/Photonis information



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Transit time spread:

- Increased voltage or decreased gap can reduce the transit time.
- Smaller pore size smaller the transit time.

MCP Gain:

- Typical secondary yield is 2 per each strike of the wall.
- L:D = 40:1 seems to be optimum design; for this ratio there are typically 10 strikes, i.e., Gain ~ 2¹⁰ ~ 10³ per single MCP plate; G ~ e^(A+L/D)
- For 10 µm dia. MCP hole, a ratio of 40:1 cannot be achieved for a 50x50 mm² size MCP (too fragile); therefore, a ratio of 60:1 is used. As a result, such MCP has slightly worse transit time.

J. Va'vra, MCP-PMT Detectors, Photonis, Brive, France

L L L L D 2/25/07

CASCADE First Order Gain (FOG) Analysis

9/23/2009

SEY Constant (First Impact)

End Spoiling in Diameters

L/D Ratio

SEY Constant (Relative to D2)

Bias Angle (Degrees)

 $MCPR(M\Omega)$ Input I(pA)

SAT Coefficient (% Strip)

1. Adams, J.; Manley, B. W., "The Mechanism of Channel Electron Multiplication," IEEE Trans. Nuc. Sci., v13, 3, p88

e. g. Adams¹ $\left(\frac{KV_{o}^{2}}{2}\right)$ Change Model with Yellow Columns Does not include tilt angle, Pore Dia, I/O Field, Charging effects FOG 2/FOG 1 **FOG 1** FOG 2 Description **Changeable Parameters** 0.6 0.6 1.00 **Open Area Ratio**

5

0.5

60

1.04

12

120

6.55

8.0%

7

0.5

62

1.35

12

100

5.28

8.0%

Before and After Emissive Coating - 60:1 LD, 12um Pitch, 12 Degree Bias



Solid line is modeled

FOG Analysis Results For GEM-D2

- 1. 40% increase in first strike SEY
- 2. 30% increase in pore cascade SEY

1.40

1.00

1.03

1.30

1.00

0.83

0.81

1.00

3. 3 % increase in apparent LD ratio



CASCADE FOG 40:1 LD 10 um Pore MCP

EXASCADE MCP FOG (V2.6.0)

MCP Mechanics

Open Area Ratio

End Spoiling (Dia)

Bias Angle (DEG)

Material Contribution

SEY (First Strike)

SEY (Pore)

MCP R (MO)

SAT Coef (%)

Input I (pA)

500

1)

2)

3)

4)

5)

6)

7)

8)

Test Conditions

Minimum Gain To Plot Measured Data Legend

B2D2 GCA-030-18

R2D2 GCA-030-19

R2D2 GCA-030-21

R2D2 GCA-030-22

R2D2 GCA-030-24

Pore Dia (um)

LD Ratio

File Save Edit Import Options Advanced

Case 1

0.6

1

5

10

41.5

5.5

1.381

119.1

6.5

9.98

Plot From (V)

Case 2 Case2/1

1.00

1.00

1.00

1.00

1.01

1.44

1.05

1000

100

I(pA)

9.30

12.30

9.54

10.48

9.98

100

8

525

33

575

8

525

675 700 725 750 800

ឆ្ល

0.6

1

5

10

42

4.9

1.34

171.5

5

10.48

R(MO)

144.3

124.9

171.5

119.1



Bias(V)

825

875

8

83

950 975 8

325



Models – (Tremsin) Macro Giudicotti¹

L. Giudicotti, Nucl. Instr. Meth. A 480 (2002) 670.

3D microscopic model with "super-electron".



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Macro-Micro Treatment TTS vs. pore diameter







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MCP CASCADE Simulation

About the model:

- MCP Cascade model is a single electron event Monte Carlo simulation of a an MCP pore and extraction parameters
- At a microscopic level, the model accounts for the following.
 - 3D geometry and potential array for flight characteristics within, and outside the pore
 - End spoiling (extraction) fields and penetration
 - Material SE characteristics including yield and SE energy
 - Cosine angular distribution of SE including normal vector correction of surface strikes based on geometry
 - Real time (event based) beam potentials and effects on SE creation
 - Real time (event based) wall charging potentials and effects on SE creation

The model predicts and reports:

- Single event gain based on input geometry, materials, and MCP bias potentials and extraction potentials
- Particle output statistics at the end of the pore, and remote anode including
 - Energy distributions
 - x', y', and r' angle distribution
 - x, y, and z velocity distribution
 - x, y, and z positions and distribution
 - Time of flight distribution
 - Tab delimited particle output files

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Standard User Interface CASCADE™

🖨 CASCADE (4.1.4)									
File Folders Options Utilities									
Current CASCADE definition file and Data Output Path									
Current File: C:\Users\DavidRBe	avidRBeaulieu\Desktop\CASCADE\CASCADE_MODEL\MCP_EXAMPLE.def								
Output Path: C:\Users\DavidRBeaulieu\Desktop\CASCADE\CASCADE_OUPUT								Save	
Build New Pore Potenial Array L/D Ratio 50 View LUA View Fly View PA Copy L/D Ratio 50 ARRADIANCE CASCADE V4.00 04/28/11 05:47:39 LD=50 L=250.0um D=5.0um B=5.0° ESi=0.5Dx5.0° ESo=2.0Dx-5.0° Pore Bias (Deg) 5 PA(V) V1= -7 V2= 700 V3= 714 ES In (D.tilt) 0.5 5 PA(V/mm) V1= 1400 V2= 2800 V3= 2800 ES In (D.tilt) 0.5 5 PA(V/mm) V1= 1400 V2= 2800 V3= 2800								Model Distributions	
ES Out (D, tilt) 2 -5	SIM: #E/SIM 1 #E/	E 1					SEA	D-SEE	
PA Size (MB) 150.8						eve de	Avalanche [Distributions	
Skip PA Refine Build PA	1 1.0 0 1 2.0 1	0Fac 2ac #S 0.5 0.0059 1 0.5 0.0074 2	#C KE8 6 361 6 199	as °as 1.1 85.2 5.0 79.9	6.00 0.00 3.50 0.00	6.0 1.0	Strike KE	Strike SE	
System Settings	1 3.0 1 1 4.0 1	2.1 0.0717 3 3.4 0.0719 5	11 247 12 163	7.7 83.0 3.1 83.4	4.33 0.00 3.20 0.00	6.0 1.5	Strike A	Wall P(V)	
Pore Diameter (mm) 0.005	1 5.0 1 1 6.0 1	3.7 0.0724 6 3.8 0.0693 7	12 139 13 129	9.0 81.3 5.1 81.2	2.83 0.00 2.57 0.14	1.0 2.0	EOP Distribu	utions	
MCP Thickness (mm) 0.25	1 7.0 1 1 8.0 1 1 9.0 1	4.2 0.0697 8 4.7 0.0664 9 5.4 0.0685 10	13 111 15 109 19 111	L.6 81.0 5.9 81.5 L.9 81.8	2.38 0.13 2.44 0.11 2.70 0.10	1.0 3.0 5.0	KE	TOF	
V1z - PC (mm) .250	1 10.0 1	5.7 0.0689 11 7.1 0.0711 12	19 104 22 105	4.1 80.9	2.55 0.09	1.0	aX	aY	
V1 Delta (-V) 350	1 12.0 1	9.4 0.0793 13	27 113	3.8 81.9 7.5 79.7	2.92 0.08	6.0			
V2 MCP (+V) 700	1 14.0 1 1 16.0 2	9.7 0.0806 15 0.2 0.0827 17	27 103 26 92	3.4 78.6 7 77.4	2.67 0.13 2.41 0.12	2.0 1.0 +	Exit Hays	J	
V3z - AN(mm) .250	•					•			
V3 Delta (+V) 700	CASCADE Event Settings Event Type Single Electron Pause First Strike Efficiency Include Beam Effects								
	# of Sims Per Event	1	Write Output	t Electrons	GV GV1	Single Event	Cance	el Fly	
FlyingComplete									

MCP CASCADE Experimental Agreement: Gain vs Bias & Endspoiling



MCP Cascade: Effect of Bias and Endspoiling

inset, from G.J. Price, G.W. Fraser / Nuclear Instruments and Methods in Physics Research A 474 (2001) 188–196





CASCADE: Prediction of Bias & Endspoiling





We can we get to ...?

Determine upper limit on $\sigma_{MCP-PMT}$

- MCP-PMT with 10 μ m holes, 64 pads, ground all pads except one being used

 - 2.33 kV with Ortec 9327 Amp/CFD (max. allowed voltage is 2.8kV => plenty of margin available for a future magnetic field operation.

Calibrate $\sigma_{Pulser + TAC_ADC}$:



Determine σ for Npe ~ 300:



(Note: $\sigma \sim 8.6$ ps with Phillips CFD 715)

Upper limit on MCP-PMT contribution to the resolution:







Analogue: Bias and timing for Mass Spec





Sub 10ps – Everything Matters





PHD Negative Exponential: first strike?

 1st Strike Fixed position

1st Strike
 Random
 position



a)

100

50

0

b) 700

Arbitrary Units

0

600

500-

400

300-

200-

100-

0

5000 10000 15000

What happens when MCP Bias is reduced?

"Monte Carlo simulations of microchannel plate detectors I: steady-state voltage bias results," M. Wu, C. Kruschwitz, D. Morgan, J. Morgan; National Security Technologies. 87544. DOE/NV/25946--400

- Lower gain due to smaller electron impact energies reducing SEY.
- Mean transit time is 23ps longer at 600 V due to decreased acceleration and increased number of electron cascades. The electrons travel a shorter distance down the channel 25000 30000 35000 40000 between collisions, and thus require more time to Electron Transit Time Distribution, 1000 V DC reach the output end.
 - TTS for the 600 V case is 20ps larger, since the spread in SE energy and direction play a greater role at lower bias voltages: electrons travel shorter distances between collisions & impact with lower energy.



Gain Histogram, 1000 V DC

20000

Gain

Mean = 182 ps

FWHM = 54 ps

Bias angle vs. resolution

"Monte Carlo simulations of microchannel plate detectors I: steady-state voltage bias results," M. Wu, C. Kruschwitz, D. Morgan, J. Morgan; National Security Technologies, 87544. DOE/NV/25946--400



ANDODE SPACING 8 MM 20 um Pore

y (um)

40um Pore

0.8

0.7

0.6

0.5

0.4

0.3

0.2

0.1

σ

0.9

0.8

0.7

0.5

0.5

0.4

0.3

0.2

0.1

σ

0.9

0.8

0.7

0.6

0.5

0.4

0.3 0.2

0.1

σ

y (um)



10 um Pore

TP 1 X/Y/I Surface Map

z(um)=611.450 BIN(um) = 0.500

Imax=1.11E+04 at (x,y: -1.0,-0.5) FWHM=7.3

y (um)

TP 1 X/Y/I Surface Map

z(um)=8000.000 BIN(um) = 20.000

Imax=2.26E+02 at (x,y: 320.0,0.0) FWHM=570.0

D

y (um)

TP 1 X/Y/I Surface Map

z(um)=8000.000 BIN(um) = 20.000

Imax=1.29E+02 at (x,y: 460.0,-20.0) FWHM=770.0

0.9

0.8

0.7

0.6

0.5

0.4

0.3

0.2

0.1

σ

0.9

0.8

0.7

0.6

0.5

0.4

0.3

0.2

0.1

σ

0.9

0.8

0.7

5 10 15 20 25

500

25

20

15

10

-10

-15

-20

-25

1000

750

500

250

-250

-500

-750

1500

1000

-1000

-500

E

× п

1000V

-25 -20 -15 -10 -5 0

Ĩ

EOP





MCP CASCADE TOF Comparison –Pore Exit

Low Yield ES

High Yield ES





At the EOF the SE yield of the ES material has little influence on TOF

MCP CASCADE TOF Comparison – Detector

Low Yield ES

High Yield ES





At the Detector the SE yield of the ES material has a significant influence on TOF. The increased low eV electrons will extend the TOF distribution to the detector. In this extreme example, a second peak can be observed for the high yield material.



LD: 60/1 L: 2400um D: 40um Tilt: 8.0deg Endspoiling: 1.0D 1.0D



Why TTS a consistent fraction of MTT?



TTS Questions – Film properties

- What is the impact of SEY on TTS (effect of gain)
 - more is better?
 - Is there an optimum?
 - Does first strike (high or low) make a difference?
- Does bandwidth (e.g. resistance) make a difference?
- What happens if you tailor the pore nanofilm properties
 USP 7408142



TTS Questions – MCP Geometry

- What is the optimal pore size, OAR, input funneling, L:D, bias angle for all of the other tradeoffs: gain, spatial resolution, timing resolution
- What is the role of endspoiling?
- What is the role of Substrate nonflatness?
- Can such a fully optimized substrate be made more than once?
- What does saturation do to TTS?What does gain do to TTS?



TTS Questions – MCP-PMT device

- What is the optimal interplate gap?
- What is the optimal bias angle for plate 1? Plate 2?
- What is the optimal pore size for plate 1? Plate 2?
- Is there advantage to a single, very high gain MCP? How does this optimization compare to the MCP geometry optimization?